

FNA41560 / FNA41560B2

Motion SPM® 45 Series

Features

- UL Certified No. E209204
- 600 V, 15 A 3 - Phase IGBT Inverter Including Control ICs for Gate Drive and Protections
- Easy PCB Layout Thanks to The Built - In Bootstrap Diodes and The Dedicated Vs Pins
- Three Separate Open - Emitter Pins from Low Side IGBTs for Three Leg Current Sensing
- Single - Grounded Power Supply with Bootstrap Operations
- Built - In NTC Thermistor for Over Temperature Monitoring
- Isolation Rating of 2000 Vrms / min.

Applications

- Motion Control - Home Appliance / Industrial Motor

Related Resources

- [AN - 9070 : Motion SPM® 45 Series Users Guide](#)
- [AN - 9071 : Motion SPM® 45 Series Thermal Performance Information](#)
- [AN - 9072 : Motion SPM® 45 Series Mounting Guidance](#)
- [RD - 344 : Reference Design \(Three Shunt Solution\)](#)
- [RD - 345 : Reference Design \(One Shunt Solution\)](#)

General Description

FNA41560 / FNA41560B2 Is A Motion SPM® 45 Series that Fairchild Has Newly Developed to Provide A Very Compact and High Performance Inverter Solution for AC Motor Drives in Low - Power Applications Such as Air Conditioners and Refrigerators. It Combines Low - Loss Short - Circuit Rated IGBTs and Optimized Gate Drivers in A Fully Isolated Package to Deliver A Simple and Robust Design. The System Reliability Is Further Enhanced by The Built - In NTC for Temperature Monitoring, Integrated Under - Voltage Lock - Out Function for Both High and Low Side, and An Over - Current Protection Input. Three Separate Open - Emitter Pins for Low Side IGBTs Make Three Leg Current Sensing Possible. Built - In Bootstrap Diodes and Dedicated VS Pins Make PCB Layout Easy.

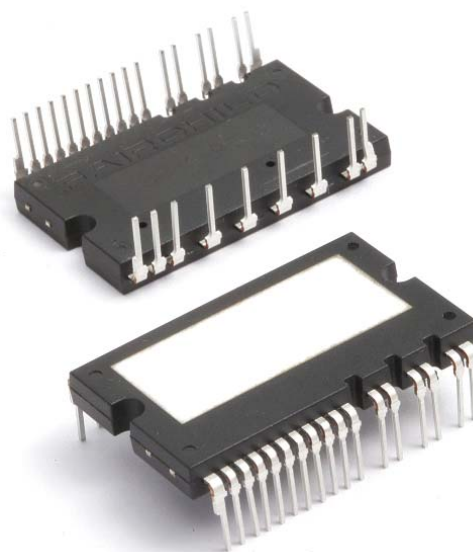


Figure 1. Package Overview

Package Marking and Ordering Information

Device Marking	Device	Package	Packing Type	Reel Size	Tape Width	Quantity
FNA41560	FNA41560	SPMAA - A26	RAIL	-	-	12
FNA41560B2	FNA41560B2	SPMAA - C26	RAIL	-	-	12

Integrated Power Functions

- 600 V - 15 A IGBT inverter for three - phase DC / AC power conversion (Please refer to Figure 3)

Integrated Drive, Protection and System Control Functions

- For inverter high - side IGBTs: Gate drive circuit, High voltage isolated high - speed level shifting
Control circuit under - voltage (UV) protection
- For inverter low - side IGBTs: Gate drive circuit, Short circuit protection (SC)
Control supply circuit under - voltage (UV) protection
- Fault signaling: Corresponding to UV (low - side supply) and SC faults
- Input interface: Active - high interface, schmitt trigger input, can work with 3.3 / 5 V logic

Pin Configuration

Top View

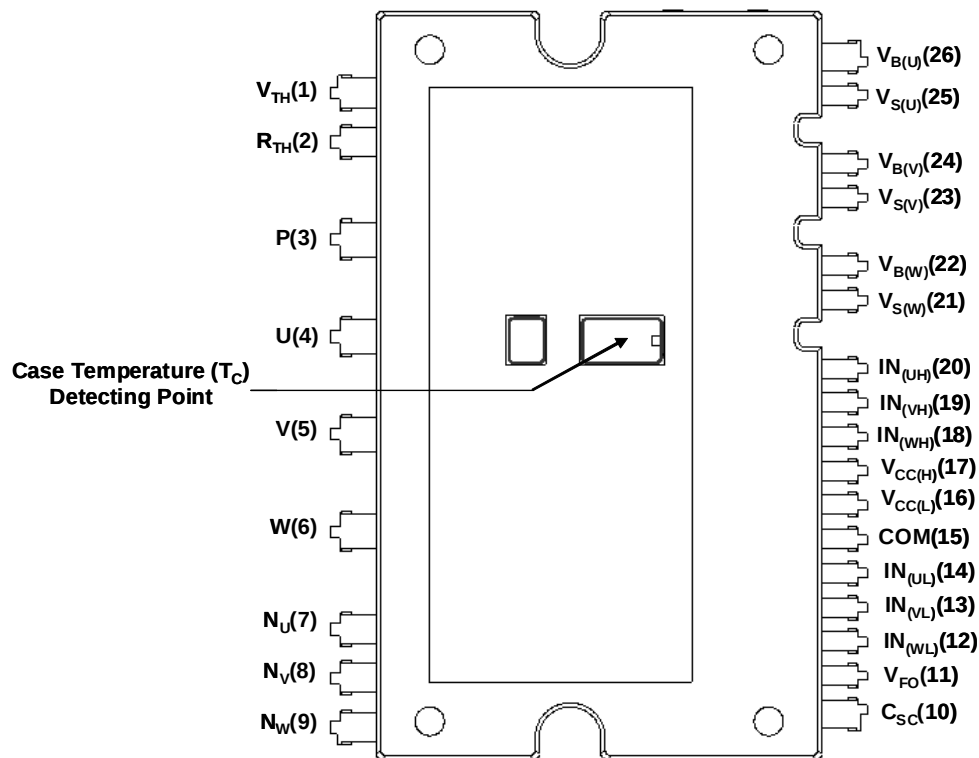
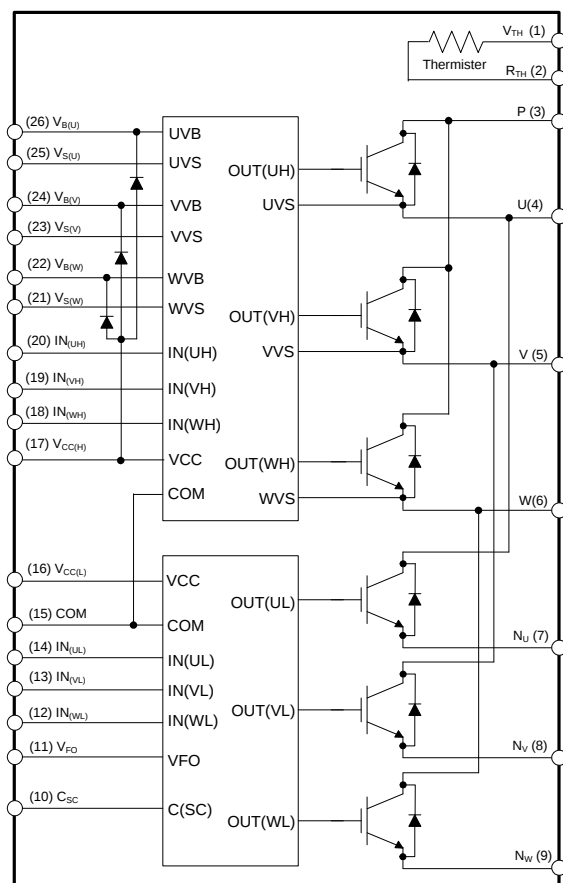


Figure 2.

Pin Descriptions

Pin Number	Pin Name	Pin Description
1	V _{TH}	Thermistor Bias Voltage
2	R _{TH}	Series Resistor for the Use of Thermistor (Temperature Detection)
3	P	Positive DC - Link Input
4	U	Output for U Phase
5	V	Output for V Phase
6	W	Output for W Phase
7	N _U	Negative DC - Link Input for U Phase
8	N _V	Negative DC - Link Input for V Phase
9	N _W	Negative DC - Link Input for W Phase
10	C _{SC}	Capacitor (Low - Pass Filter) for Short - Current Detection Input
11	V _{FO}	Fault Output
12	IN _(WL)	Signal Input for Low - Side W Phase
13	IN _(VL)	Signal Input for Low - Side V Phase
14	IN _(UL)	Signal Input for Low - Side U Phase
15	COM	Common Supply Ground
16	V _{CC(L)}	Low - Side Common Bias Voltage for IC and IGBTs Driving
17	V _{CC(H)}	High - Side Common Bias Voltage for IC and IGBTs Driving
18	IN _(WH)	Signal Input for High - Side W Phase
19	IN _(VH)	Signal Input for High - Side V Phase
20	IN _(UH)	Signal Input for High - Side U Phase
21	V _{S(W)}	High - Side Bias Voltage Ground for W Phase IGBT Driving
22	V _{B(W)}	High - Side Bias Voltage for W Phase IGBT Driving
23	V _{S(V)}	High - Side Bias Voltage Ground for V Phase IGBT Driving
24	V _{B(V)}	High - Side Bias Voltage for V Phase IGBT Driving
25	V _{S(U)}	High - Side Bias Voltage Ground for U Phase IGBT Driving
26	V _{B(U)}	High - Side Bias Voltage for U Phase IGBT Driving

Internal Equivalent Circuit and Input/Output Pins



Note:

- 1) Inverter high - side is composed of three IGBTs, freewheeling diodes and one control IC for each IGBT.
- 2) Inverter low - side is composed of three IGBTs, freewheeling diodes and one control IC for each IGBT. It has gate drive and protection functions.
- 3) Inverter power side is composed of four inverter dc - link input terminals and three inverter output terminals.

Figure 3.

Absolute Maximum Ratings ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)**Inverter Part**

Symbol	Parameter	Conditions	Rating	Unit
V_{PN}	Supply Voltage	Applied between P - N_U , N_V , N_W	450	V
$V_{PN(\text{Surge})}$	Supply Voltage (Surge)	Applied between P - N_U , N_V , N_W	500	V
V_{CES}	Collector - Emitter Voltage		600	V
$\pm I_C$	Each IGBT Collector Current	$T_C = 25^\circ\text{C}$, $T_J < 150^\circ\text{C}$	15	A
$\pm I_{CP}$	Each IGBT Collector Current (Peak)	$T_C = 25^\circ\text{C}$, $T_J < 150^\circ\text{C}$, Under 1 ms Pulse Width	30	A
P_C	Collector Dissipation	$T_C = 25^\circ\text{C}$ per One Chip	41	W
T_J	Operating Junction Temperature	(Note 1)	- 40 ~ 150	$^\circ\text{C}$

Note:

1. The maximum junction temperature rating of the power chips integrated within the Motion SPM® 45 product is 150°C .

Control Part

Symbol	Parameter	Conditions	Rating	Unit
V_{CC}	Control Supply Voltage	Applied between $V_{CC(H)}$, $V_{CC(L)}$ - COM	20	V
V_{BS}	High - Side Control Bias Voltage	Applied between $V_{B(U)}$ - $V_{S(U)}$, $V_{B(V)}$ - $V_{S(V)}$, $V_{B(W)}$ - $V_{S(W)}$	20	V
V_{IN}	Input Signal Voltage	Applied between $IN_{(UH)}$, $IN_{(VH)}$, $IN_{(WH)}$, $IN_{(UL)}$, $IN_{(VL)}$, $IN_{(WL)}$ - COM	- 0.3 ~ $V_{CC} + 0.3$	V
V_{FO}	Fault Output Supply Voltage	Applied between V_{FO} - COM	- 0.3 ~ $V_{CC} + 0.3$	V
I_{FO}	Fault Output Current	Sink Current at V_{FO} pin	1	mA
V_{SC}	Current Sensing Input Voltage	Applied between C_{SC} - COM	- 0.3 ~ $V_{CC} + 0.3$	V

Bootstrap Diode Part

Symbol	Parameter	Conditions	Rating	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage		600	V
I_F	Forward Current	$T_C = 25^\circ\text{C}$, $T_J < 150^\circ\text{C}$	0.50	A
I_{FP}	Forward Current (Peak)	$T_C = 25^\circ\text{C}$, $T_J < 150^\circ\text{C}$, Under 1 ms Pulse Width	1.50	A
T_J	Operating Junction Temperature		- 40 ~ 150	$^\circ\text{C}$

Total System

Symbol	Parameter	Conditions	Rating	Unit
$V_{PN(\text{PROT})}$	Self Protection Supply Voltage Limit (Short Circuit Protection Capability)	$V_{CC} = V_{BS} = 13.5 \sim 16.5 \text{ V}$ $T_J = 150^\circ\text{C}$, Non - repetitive, less than 2 μs	400	V
T_{STG}	Storage Temperature		- 40 ~ 125	$^\circ\text{C}$
V_{ISO}	Isolation Voltage	60 Hz, Sinusoidal, AC 1 minute, Connection pins to heat sink plate	2000	V_{rms}

Thermal Resistance

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{th(j-c)Q}$	Junction to Case Thermal Resistance	Inverter IGBT part (per 1 / 6 module)	-	-	3.0	$^\circ\text{C} / \text{W}$
$R_{th(j-c)F}$		Inverter FWD part (per 1 / 6 module)	-	-	4.3	$^\circ\text{C} / \text{W}$

Note:

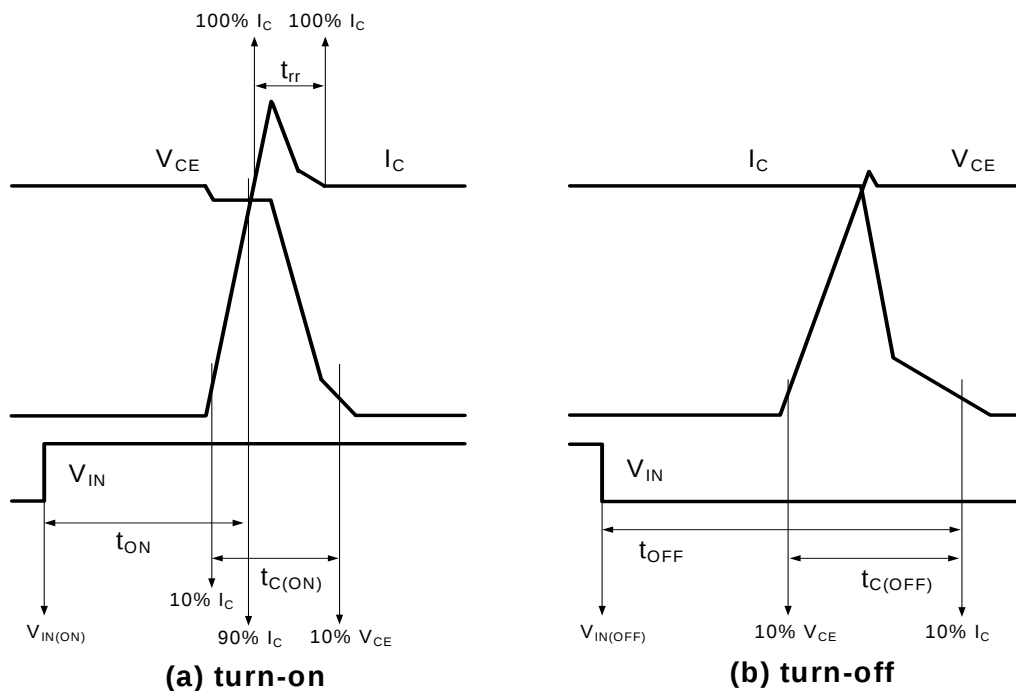
2. For the measurement point of case temperature (T_C), please refer to Figure 2.

Electrical Characteristics ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)**Inverter Part**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{CE(SAT)}$	Collector - Emitter Saturation Voltage	$V_{CC} = V_{BS} = 15\text{ V}$ $V_{IN} = 5\text{ V}$ $I_C = 15\text{ A}$, $T_J = 25^\circ\text{C}$	-	1.8	2.3	V
V_F	FWD Forward Voltage	$V_{IN} = 0\text{ V}$ $I_F = 15\text{ A}$, $T_J = 25^\circ\text{C}$	-	1.8	2.3	V
HS	t_{ON}	$V_{PN} = 300\text{ V}$, $V_{CC} = V_{BS} = 15\text{ V}$, $I_C = 15\text{ A}$ $T_J = 25^\circ\text{C}$ $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$, Inductive load (Note 3)	0.45	0.75	1.25	μs
	$t_{C(ON)}$		-	0.25	0.50	μs
	t_{OFF}		-	0.75	1.25	μs
	$t_{C(OFF)}$		-	0.25	0.50	μs
	t_{rr}		-	0.15	-	μs
LS	t_{ON}	$V_{PN} = 300\text{ V}$, $V_{CC} = V_{BS} = 15\text{ V}$, $I_C = 15\text{ A}$ $T_J = 25^\circ\text{C}$ $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$, Inductive load (Note 3)	0.45	0.75	1.25	μs
	$t_{C(ON)}$		-	0.25	0.50	μs
	t_{OFF}		-	0.75	1.25	μs
	$t_{C(OFF)}$		-	0.25	0.50	μs
	t_{rr}		-	0.15	-	μs
I_{CES}	Collector - Emitter Leakage Current	$V_{CE} = V_{CES}$	-	-	1	mA

Note:

3. t_{ON} and t_{OFF} include the propagation delay time of the internal drive IC. $t_{C(ON)}$ and $t_{C(OFF)}$ are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

**Figure 4. Switching Time Definition**

Switching Loss (Typical)

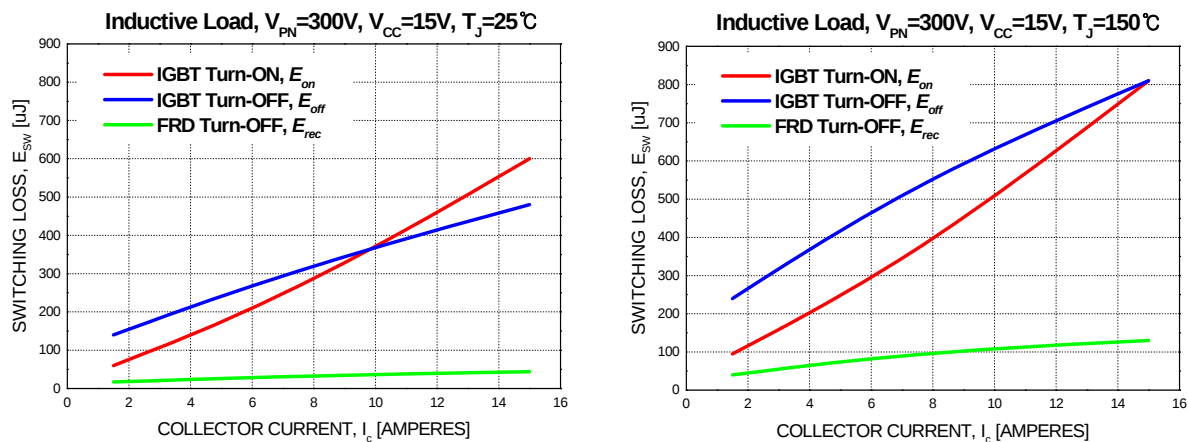


Figure 5. Switching Loss Characteristics

Control Part

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_{QCCH}	Quiescent V_{CC} Supply Current	$V_{CC(H)} = 15 V$, $I_{N(UH, VH, WH)} = 0 V$	$V_{CC(H)} - COM$	-	-	0.10 mA
I_{QCCL}		$V_{CC(L)} = 15 V$, $I_{N(UL, VL, WL)} = 0 V$	$V_{CC(L)} - COM$	-	-	2.65 mA
I_{PCCH}	Operating V_{CC} Supply Current	$V_{CC(H)} = 15 V$, $f_{PWM} = 20 kHz$, duty = 50%, applied to one PWM signal input for high - side	$V_{CC(H)} - COM$	-	-	0.15 mA
I_{PCCL}		$V_{CC(L)} = 15 V$, $f_{PWM} = 20 kHz$, duty = 50%, applied to one PWM signal input for low - side	$V_{CC(L)} - COM$	-	-	3.65 mA
I_{QBS}	Quiescent V_{BS} Supply Current	$V_{BS} = 15 V$, $I_{N(UH, VH, WH)} = 0 V$	$V_{B(U)} - V_{S(U)}$, $V_{B(V)} - V_{S(V)}$, $V_{B(W)} - V_{S(W)}$	-	-	0.30 mA
I_{PBS}	Operating V_{BS} Supply Current	$V_{CC} = V_{BS} = 15 V$, $f_{PWM} = 20 kHz$, duty = 50%, applied to one PWM signal input for high - side	$V_{B(U)} - V_{S(U)}$, $V_{B(V)} - V_{S(V)}$, $V_{B(W)} - V_{S(W)}$	-	-	2.00 mA
V_{FOH}	Fault Output Voltage	$V_{SC} = 0 V$, V_{FO} Circuit: 10 k Ω to 5 V Pull - up	4.5	-	-	V
V_{FOL}		$V_{SC} = 1 V$, V_{FO} Circuit: 10 k Ω to 5 V Pull - up	-	-	0.5	V
$V_{SC(ref)}$	Short Circuit Trip Level	$V_{CC} = 15 V$ (Note 4)	0.45	0.5	0.55	V
UV_{CCD}	Supply Circuit Under - Voltage Protection	Detection level	10.5	-	13.0	V
UV_{CCR}		Reset level	11.0	-	13.5	V
UV_{BSD}		Detection level	10.0	-	12.5	V
UV_{BSR}		Reset level	10.5	-	13.0	V
t_{FOD}	Fault - Out Pulse Width		30	-	-	μs
$V_{IN(ON)}$	ON Threshold Voltage	Applied between $I_{N(UH)}$, $I_{N(VH)}$, $I_{N(WH)}$, $I_{N(UL)}$, $I_{N(VL)}$, $I_{N(WL)} - COM$	-	-	2.6	V
$V_{IN(OFF)}$	OFF Threshold Voltage		0.8	-	-	V
R_{TH}	Resistance of Thermister	@ $T_{TH} = 25^\circ C$, (Note 5)	-	47	-	k Ω
		@ $T_{TH} = 100^\circ C$	-	2.9	-	k Ω

Note:

- Short - circuit current protection is functioning only at the low - sides.
- T_{TH} is the temperature of thermister itself. To know case temperature (T_C), please make the experiment considering your application.

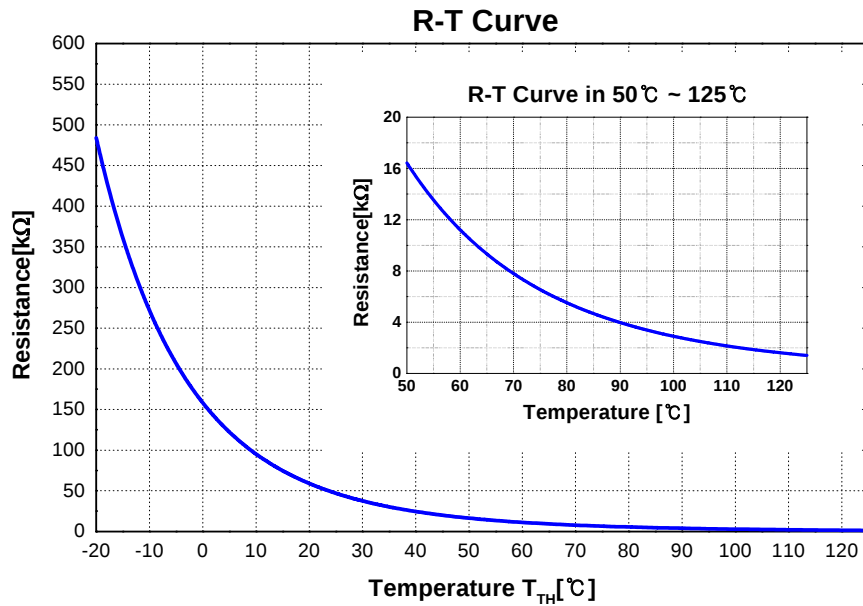
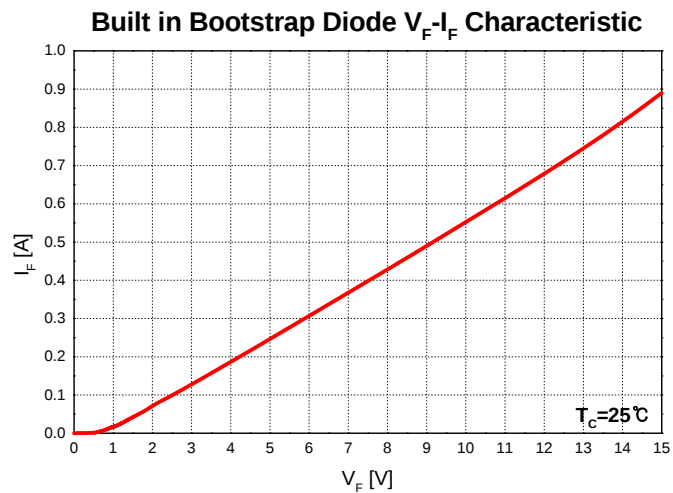


Figure. 6. R-T Curve of The Built-in Thermistor

Bootstrap Diode Part

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F = 0.1 \text{ A}$, $T_C = 25^\circ\text{C}$	-	2.5	-	V
t_{rr}	Reverse Recovery Time	$I_F = 0.1 \text{ A}$, $T_C = 25^\circ\text{C}$	-	80	-	ns



Note:

6. Built in bootstrap diode includes around 15 Ω resistance characteristic.

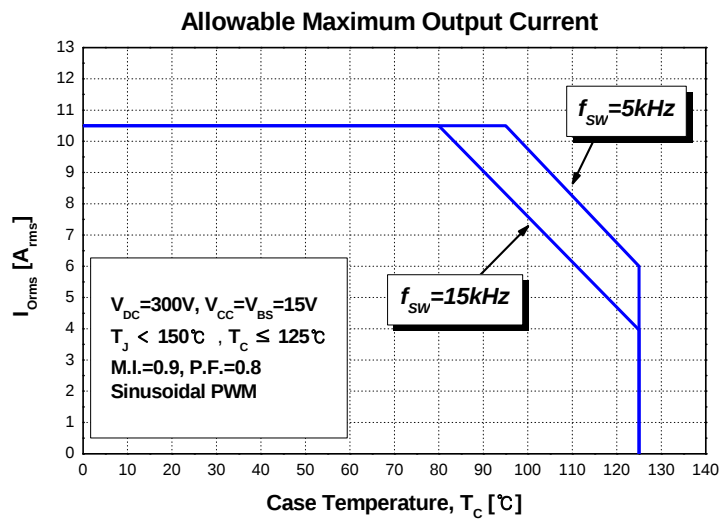
Figure 7. Built in Bootstrap Diode Characteristic

Recommended Operating Conditions

Symbol	Parameter	Conditions	Value			Unit
			Min.	Typ.	Max.	
V_{PN}	Supply Voltage	Applied between P - N_U , N_V , N_W	-	300	400	V
V_{CC}	Control Supply Voltage	Applied between $V_{CC(H)}$, $V_{CC(L)}$ - COM	13.5	15	16.5	V
V_{BS}	High - Side Bias Voltage	Applied between $V_{B(U)}$ - $V_{S(U)}$, $V_{B(V)}$ - $V_{S(V)}$, $V_{B(W)}$ - $V_{S(W)}$	13.0	15	18.5	V
dV_{CC}/dt , dV_{BS}/dt	Control Supply Variation		- 1	-	1	V / μ s
t_{dead}	Blanking Time for Preventing Arm - Short	For each input signal	1.5	-	-	μ s
f_{PWM}	PWM Input Signal	$-40^{\circ}\text{C} < T_J < 150^{\circ}\text{C}$	-	-	20	kHz
V_{SEN}	Voltage for Current Sensing	Applied between N_U , N_V , N_W - COM (Including surge voltage)	- 4		4	V
$P_{WIN(ON)}$	Minimum Input Pulse Width	(Note 7)	0.5	-	-	μ s
$P_{WIN(OFF)}$			0.5	-	-	

Note:

7. This product might not make response if input pulse width is less than the recommended value.



Note:

8. This allowable output current value is the reference data for the safe operation of this product. This may be different from the actual application and operating condition.

Figure 8. Allowable Maximum Output Current

Mechanical Characteristics and Ratings

Parameter	Conditions	Limits			Unit
		Min.	Typ.	Max.	
Device Flatness	Note Figure 9	0	-	+ 120	μm
Mounting Torque	Mounting Screw: - M3	Recommended 0.7 N • m			N • m
	Note Figure 10	Recommended 7.1 kg • cm			kg • cm
Weight		-	11	-	g

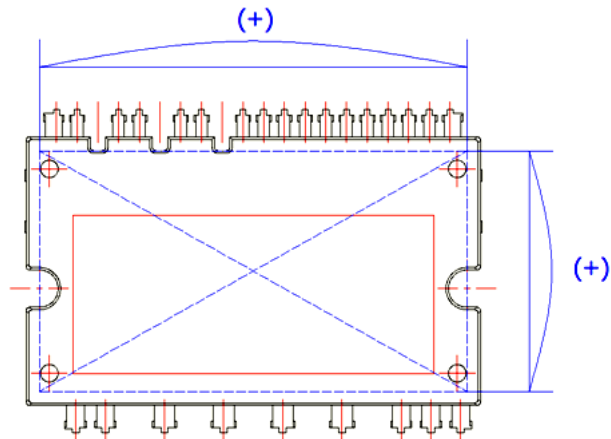
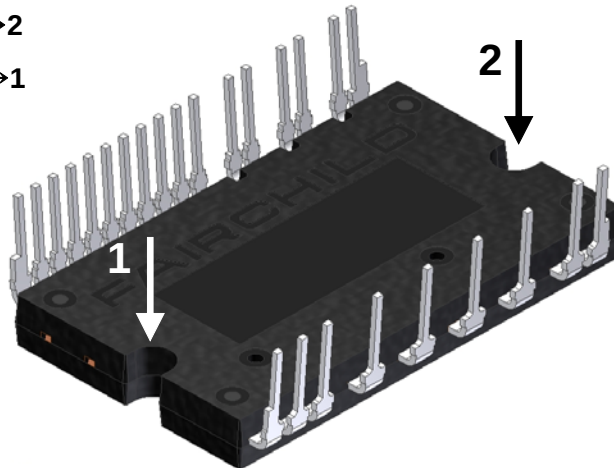


Figure 9. Flatness Measurement Position

Pre - Screwing : 1→2

Final Screwing : 2→1

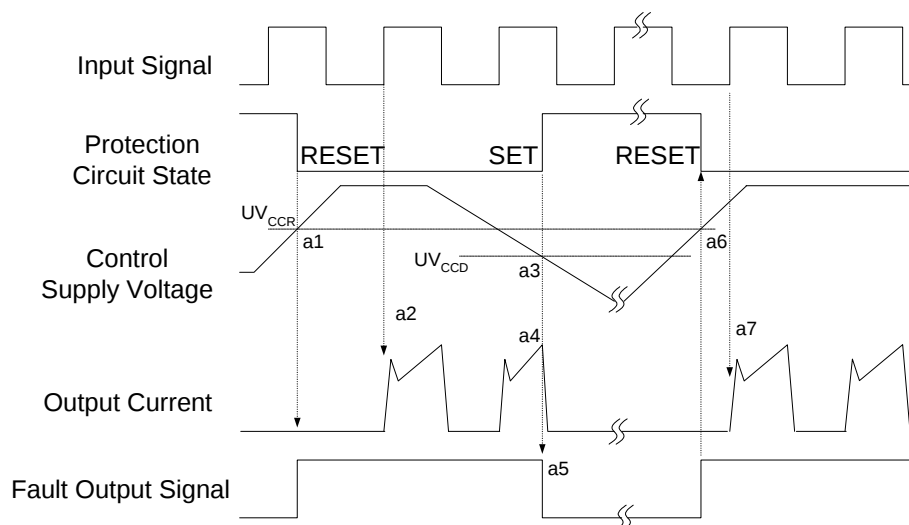


Note:

9. Do not make over torque when mounting screws. Much mounting torque may cause ceramic cracks, as well as bolts and Al heat - sink destruction.
10. Avoid one side tightening stress. Figure 10 shows the recommended torque order for mounting screws. Uneven mounting can cause the ceramic substrate of the Motion SPM® 45 product to be damaged. The Pre - Screwing torque is set to 20 ~ 30% of maximum torque rating.

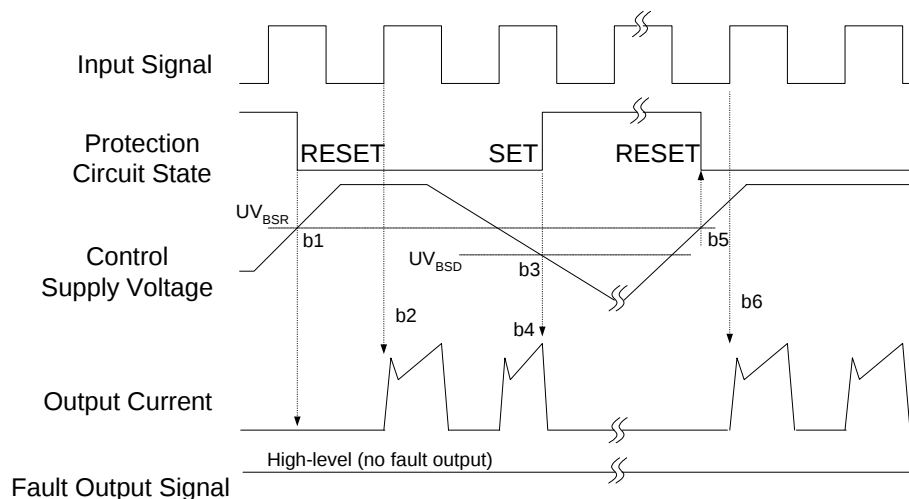
Figure 10. Mounting Screws Torque Order

Time Charts of Protective Function



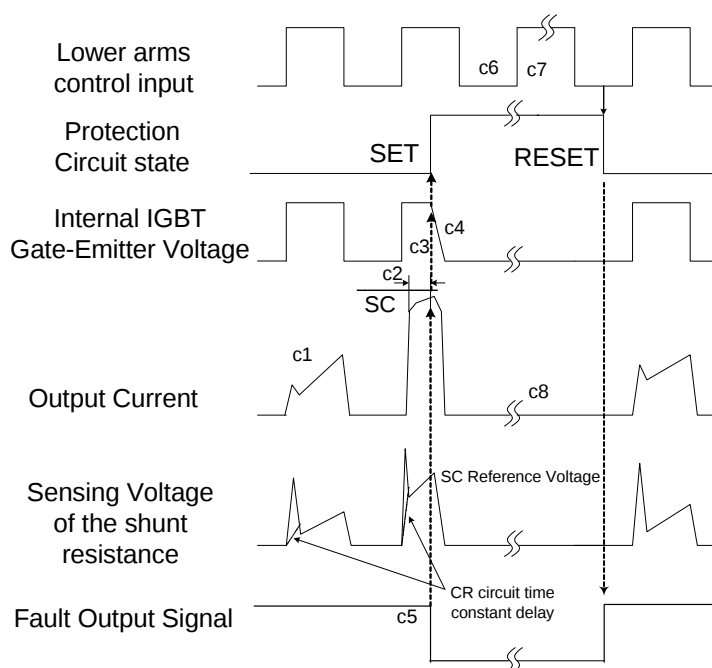
- a1 : Control supply voltage rises: After the voltage rises UV_{CCR} , the circuits start to operate when next input is applied.
- a2 : Normal operation: IGBT ON and carrying current.
- a3 : Under voltage detection (UV_{CCD}).
- a4 : IGBT OFF in spite of control input condition.
- a5 : Fault output operation starts.
- a6 : Under voltage reset (UV_{CCR}).
- a7 : Normal operation: IGBT ON and carrying current.

Figure 11. Under - Voltage Protection (Low - Side)



- b1 : Control supply voltage rises: After the voltage reaches UV_{BSR} , the circuits start to operate when next input is applied.
- b2 : Normal operation: IGBT ON and carrying current.
- b3 : Under voltage detection (UV_{BSD}).
- b4 : IGBT OFF in spite of control input condition, but there is no fault output signal.
- b5 : Under voltage reset (UV_{BSR})
- b6 : Normal operation: IGBT ON and carrying current

Figure 12. Under - Voltage Protection (High - Side)



(with the external shunt resistance and CR connection)

c1 : Normal operation: IGBT ON and carrying current.

c2 : Short circuit current detection (SC trigger).

c3 : Hard IGBT gate interrupt.

c4 : IGBT turns OFF.

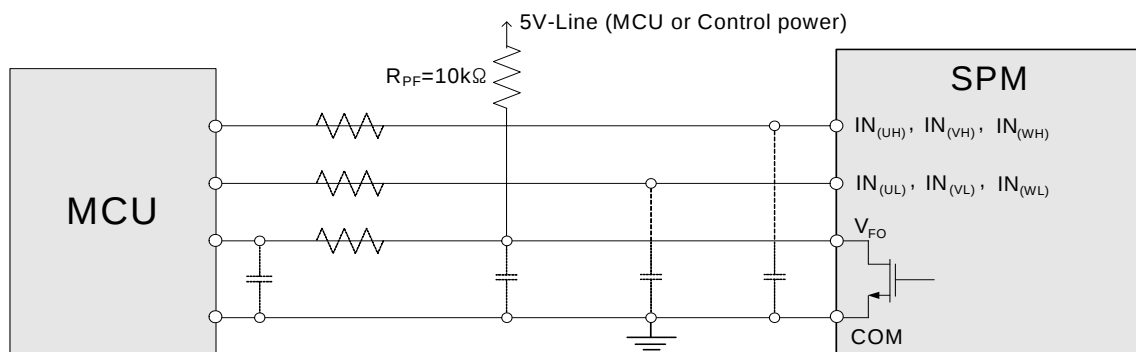
c5 : Input "L" : IGBT OFF state.

c6 : Input "H": IGBT ON state, but during the active period of fault output the IGBT doesn't turn ON.

c7 : IGBT OFF state

Figure 13. Short - Circuit Current Protection (Low - Side Operation only)

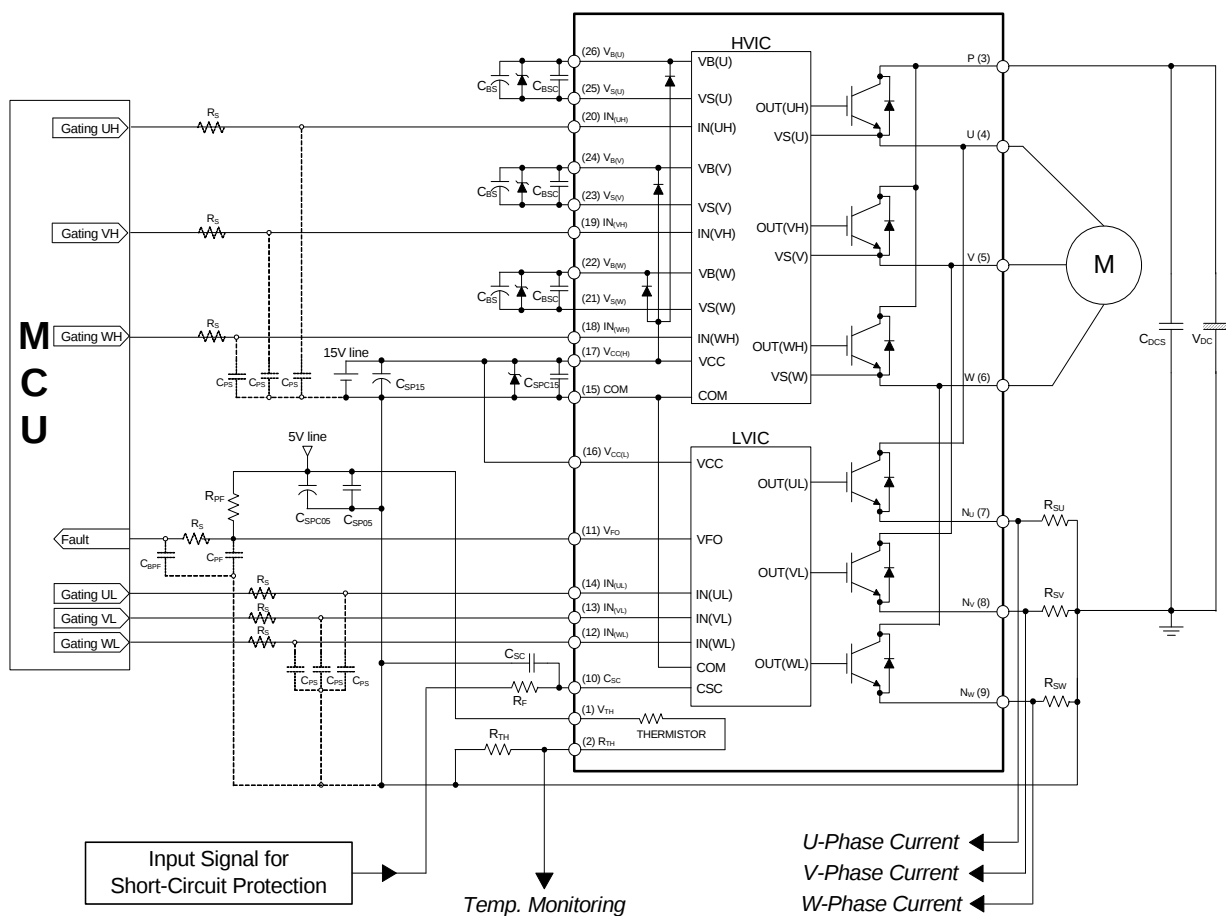
Input/Output Interface Circuit



Note:

- 1) RC coupling at each input (parts shown dotted) might change depending on the PWM control scheme used in the application and the wiring impedance of the application's printed circuit board. The input signal section of the Motion SPM® 45 product integrates 5 k Ω (typ.) pull - down resistor. Therefore, when using an external filtering resistor, please pay attention to the signal voltage drop at input terminal.
- 2) The logic input is compatible with standard CMOS outputs.

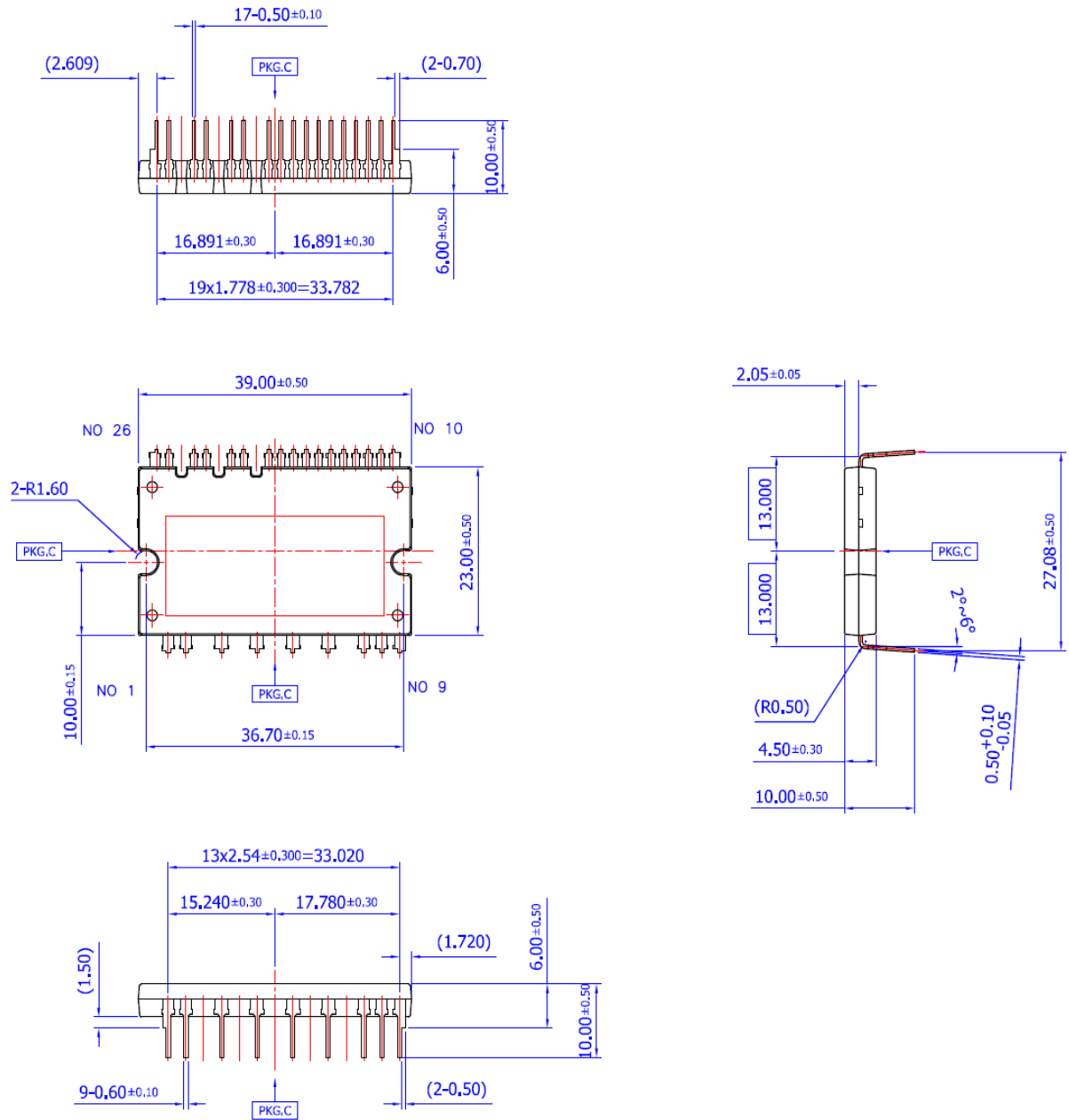
Figure 14. Recommended CPU I/O Interface Circuit

**Note:**

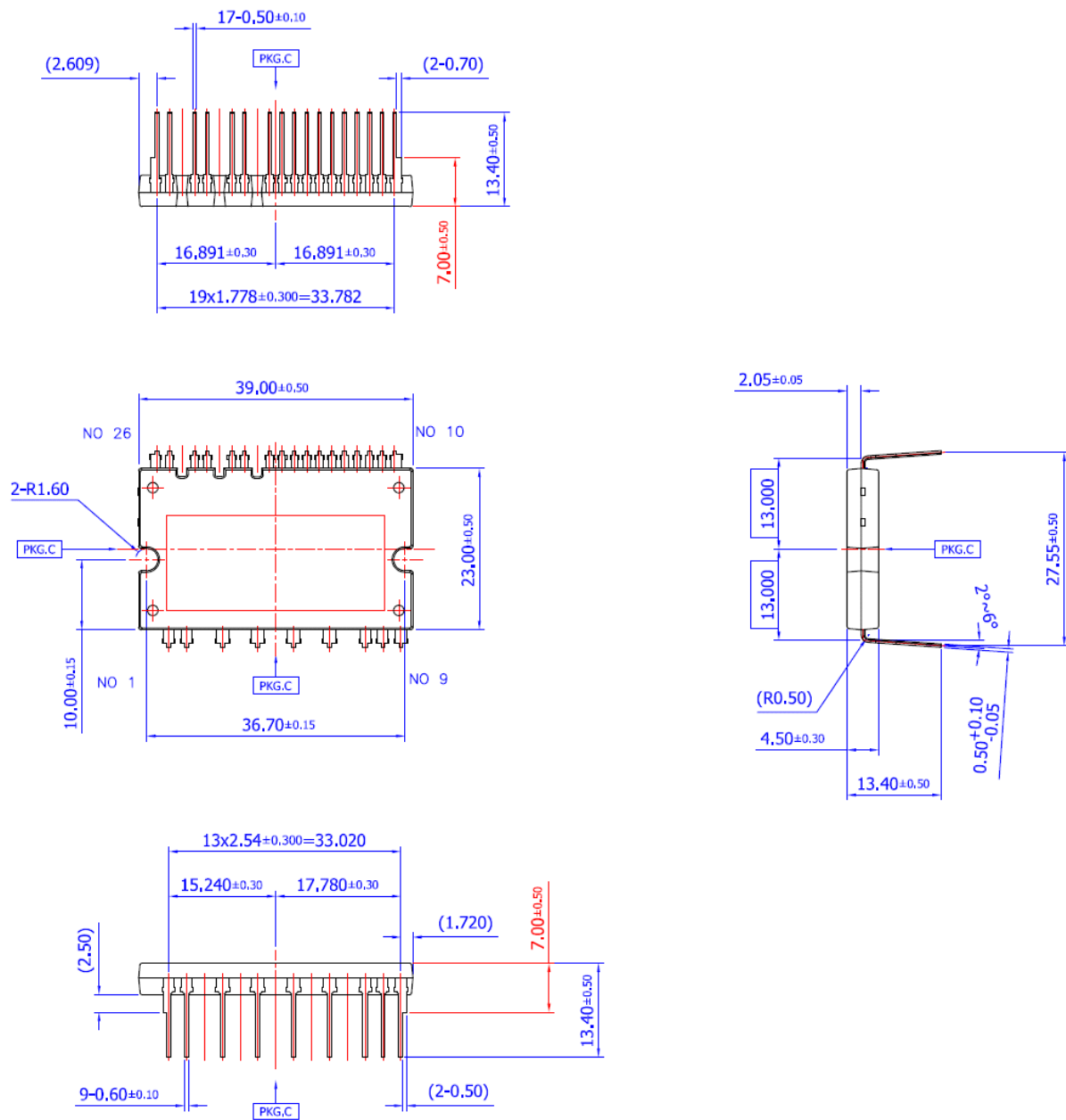
- 1) To avoid malfunction, the wiring of each input should be as short as possible. (less than 2 - 3 cm)
- 2) By virtue of integrating an application specific type HVIC inside the Motion SPM® 45 product, direct coupling to CPU terminals without any opto - coupler or transformer isolation is possible.
- 3) VFO output is open drain type. This signal line should be pulled up to the positive side of the MCU or control power supply with a resistor that makes I_{FO} up to 1 mA. Please refer to Figure 14.
- 4) C_{SP15} of around 7 times larger than bootstrap capacitor C_{BS} is recommended.
- 5) Input signal is High - Active type. There is a 5 kΩ resistor inside the IC to pull down each input signal line to GND. RC coupling circuits is recommended for the prevention of input signal oscillation. R_SC_{PS} time constant should be selected in the range 50 ~ 150 ns. (Recommended R_S = 100 Ω, C_{PS} = 1 nF)
- 6) To prevent errors of the protection function, the wiring around R_F and C_{SC} should be as short as possible.
- 7) In the short - circuit protection circuit, please select the R_FC_{SC} time constant in the range 1.5 ~ 2 μs.
- 8) Each capacitor should be mounted as close to the pins of the SPM as possible.
- 9) To prevent surge destruction, the wiring between the smoothing capacitor and the P & GND pins should be as short as possible. The use of a high frequency non - inductive capacitor of around 0.1 ~ 0.22 μF between the P & GND pins is recommended.
- 10) Relays are used at almost every systems of electrical equipments of home appliances. In these cases, there should be sufficient distance between the CPU and the relays.
- 11) The zener diode should be adopted for the protection of ICs from the surge destruction between each pair of control supply terminals. (Recommended zener diode = 22 V / 1 W)
- 12) Please choose the electrolytic capacitor with good temperature characteristic in C_{BS}. Also, choose 0.1 ~ 0.2 μF R - category ceramic capacitors with good temperature and frequency characteristics in C_{BSC}.
- 13) For the detailed information, please refer to the AN - 9070, AN - 9071, AN - 9072, RD - 344, and RD - 345.

Figure 15. Typical Application Circuit

Detailed Package Outline Drawings (FNA41560)



Detailed Package Outline Drawings (FNA41560B2, Long Terminal Type)



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Build it Now™	GreenBridge™	QFET®	TinyCalc™
CorePLUS™	Green FPS™	QS™	TinyLogic®
CorePOWER™	Green FPS™ e-Series™	Quiet Series™	TINYOPTO™
CROSSVOLT™	Gmax™	RapidConfigure™	TinyPower™
CTL™	GTO™		TinyPWM™
Current Transfer Logic™	IntelliMAX™	Saving our world, 1mW/W/kW at a time™	TinyWire™
DEUXPEED®	ISOPLANAR™	SignalWise™	TranSiC™
Dual Cool™	Making Small Speakers Sound Louder and Better™	SmartMax™	TriFault Detect™
EcoSPARK®	MegaBuck™	SMART START™	TRUECURRENT®*
EfficientMax™	MICROCOUPLER™	Solutions for Your Success™	μSerDes™
ESBC™	MicroFET™	SPM®	 SerDes®
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Fairchild Semiconductor®	MicroPak2™	SuperFET®	Ultra FRFET™
FACT Quiet Series™	MillerDrive™	SuperSOT™-3	UniFET™
FACT®	MotionMax™	SuperSOT™-6	VCX™
FAST®	mWSaver™	SuperSOT™-8	VisualMax™
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Definition of Terms

Datasheet Identification	Product Status	Definition
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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